ICS 31.180 SLOVENSKÁ TECHNICKÁ NORMA Október 2016

STN	**Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy. Časť 3-719: Skúšobné metódy na spájacie štruktúry (dosky s plošnými spojmi). Monitorovanie zmien odporu na jednoduchých doskách s pokovovanými otvormi (PTH) počas cyklických tepelných skúšok.**	**STN EN 61189-3-719** 34 6513

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-719: Test methods for interconnection structures (printed boards) - Monitoring of single plated-through hole (PTH) resistance change during temperature cycling

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 09/16

Obsahuje: EN 61189-3-719:2016, IEC 61189-3-719:2016

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 61189-3-719

April 2016

ICS 31.180

English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-719: Test methods for interconnection structures (printed boards) - Monitoring of single plated-through hole (PTH) resistance change during temperature cycling (IEC 61189-3-719:2016)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 3-719: Méthodes d'essai pour les structures d'interconnexion (cartes imprimées) - Contrôles de la variation de résistance des trous métallisés uniques (PTH) au cours des cycles thermiques (IEC 61189-3-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 3-719: Prüfverfahren für Verbindungsstrukturen (Leiterplatten) - Überwachung des Widerstands von Einzeldurchkontaktierungen (PTH - plated-through hole) bei Temperaturwechselbeanspruchung (IEC 61189-3-719:2016)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

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European foreword

The text of document 91/1303/FDIS, future edition 1 of IEC 61189-3-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-3-719:2016.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2016-11-09
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2019-02-09

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The text of the International Standard IEC 61189-3-719:2016 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)
Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60068-2-14	-	Environmental testing -- Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-58	2015	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	2015
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IPC-2221	-	Generic Standard on Printed Board Design	-	-

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CONTENTS

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 3-719: Test methods for interconnection structures (printed boards) – Monitoring of single plated-through hole (PTH) resistance change during temperature cycling

FOREWORD

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International Standard IEC 61189-3-719 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1303/FDIS	91/1327/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies* can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 3-719: Test methods for interconnection structures (printed boards) – Monitoring of single plated-through hole (PTH) resistance change during temperature cycling

1 Scope

This part of IEC 61189 specifies a test method to monitor the resistance of single plated-through holes (PTHs) in printed circuit boards (PCBs) to determine the PTH durability under thermo-mechanical stress induced by temperature cycling.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-14, *Environmental testing – Part 2-14: Tests – Test N: Change of temperature*

IEC 60068-2-58:2015, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

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